

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Examiner: Khiem D. Nguyen
Toshikazu Okubo et al.

Serial No. 10/550,153 Art Unit: 2823

Filed: September 20, 2005 Confirmation No.: 1053

Title: Method for Analyzing Copper Electroplating Solution, Apparatus for the Analysis, and Method for Fabricating Semiconductor Product

RESPONSE TO OFFICE ACTION

Dear Examiner Nguyen:

This is a response to the Office Action dated July 3, 2008, which has a shortened statutory period for reply that ends on October 3, 2008. Please amend the above-identified application as follows.

Amendments to the Claims begins on page 2 of this paper.

Remarks begin on page 10 of this paper.